

Surface Mount Schottky Power Rectifier

MBRS3200T3G, NRVBS3200T3G, NRVBS3200NT3G

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very High Blocking Voltage – 200 V
- 175°C Operating Junction Temperature
- Guard-Ring for Stress Protection
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements: AEC-Q101 Qualified and PPAP Capable*
- These are Pb-Free Devices

Mechanical Characteristics

- Case: Epoxy, Molded, Epoxy Meets UL 94, V-0
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Cathode Polarity Band
- Device Meets MSL 1 Requirements
- ESD Ratings:
 - ◆ Machine Model = A
 - ◆ Human Body Model = 1C



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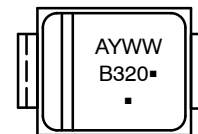
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SCHOTTKY BARRIER RECTIFIER 3.0 AMPERE 200 VOLTS



SMB
CASE 403A

MARKING DIAGRAM



B320 = Specific Device Code
A = Assembly Location**
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|------------------|------------------------|
| MBRS3200T3G | SMB (Pb-Free) | 2,500 / Tape & Reel |
| NRVBS3200T3G* | SMB (Pb-Free) | 2,500 / Tape & Reel |
| NRVBS3200NT3G* | SMB (Pb-Free) | 2,500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MBRS3200T3G, NRVBS3200T3G, NRVBS3200NT3G

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 200 | V |
| Average Rectified Forward Current ($T_L = 150^\circ\text{C}$) | $I_{F(AV)}$ | 3.0 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I_{FSM} | 100 | A |
| Operating Junction Temperature | T_J | -65 to +175 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|-----------------|-------|--------------------|
| Thermal Resistance, Junction-to-Lead (Note 1) | $R_{\theta JL}$ | 13 | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 62 | $^\circ\text{C/W}$ |

ELECTRICAL CHARACTERISTICS

| | | | |
|--|-------|----------------------|----------|
| Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 3.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 4.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 3.0\text{ A}$, $T_J = 150^\circ\text{C}$) | V_F | 0.84 0.86 0.59 | V |
| Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 25^\circ\text{C}$) (Rated dc Voltage, $T_J = 150^\circ\text{C}$) | I_R | 1.0 5.0 | mA mA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Minimum pad size (0.108 × 0.085 inch) for each lead on FR4 board.
2. 1 inch square pad size (1 × 0.5 inch) for each lead on FR4 board.
3. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.



Figure 1. Typical Forward Voltage



Figure 2. Maximum Forward Voltage

MBRS3200T3G, NRVBS3200T3G, NRVBS3200NT3G

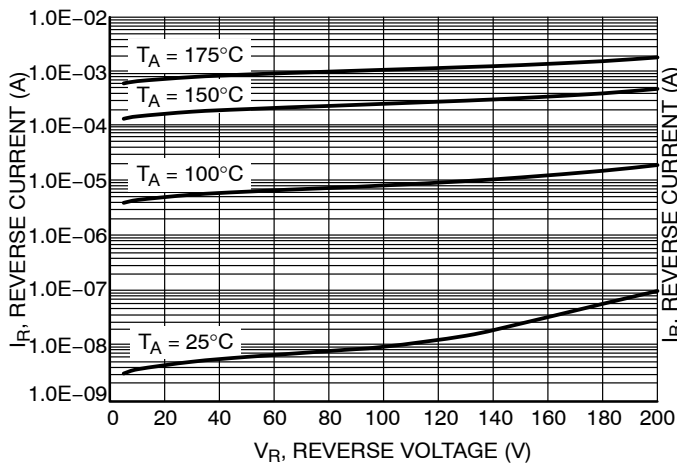


Figure 3. Typical Reverse Current

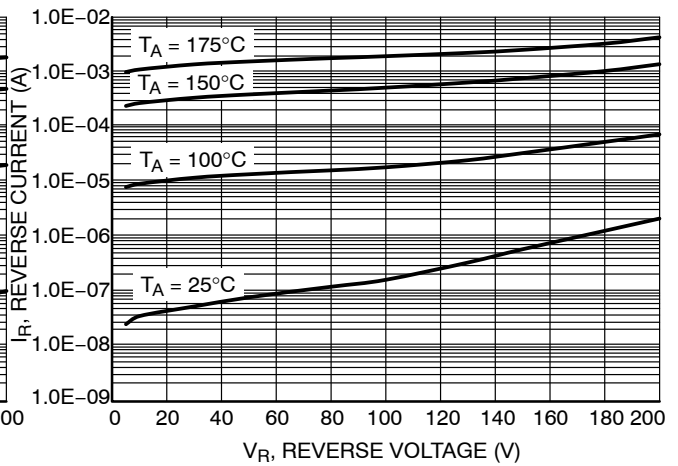


Figure 4. Maximum Reverse Current

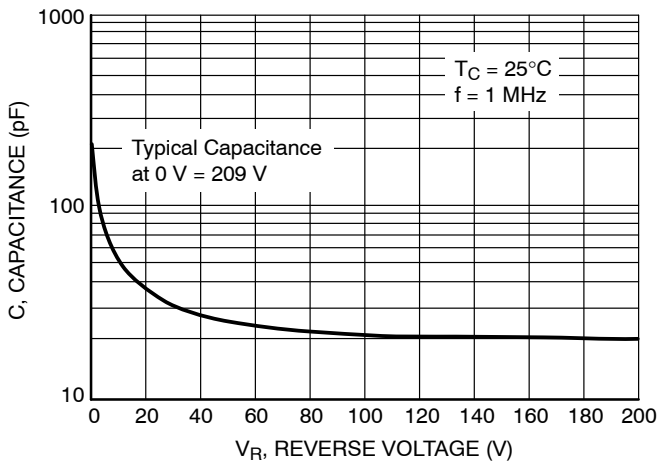


Figure 5. Typical Capacitance

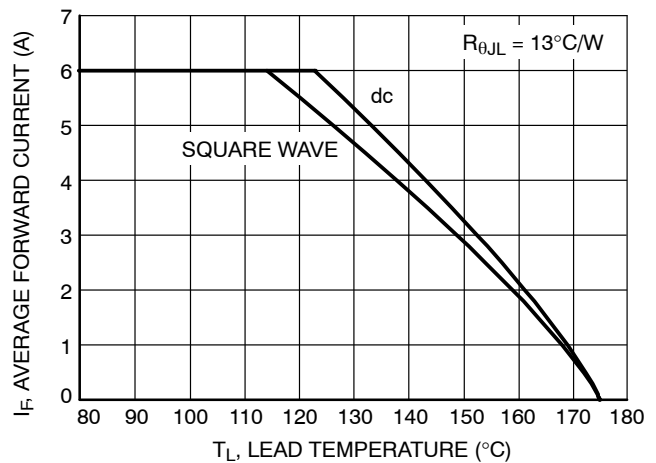


Figure 6. Current Derating - Lead

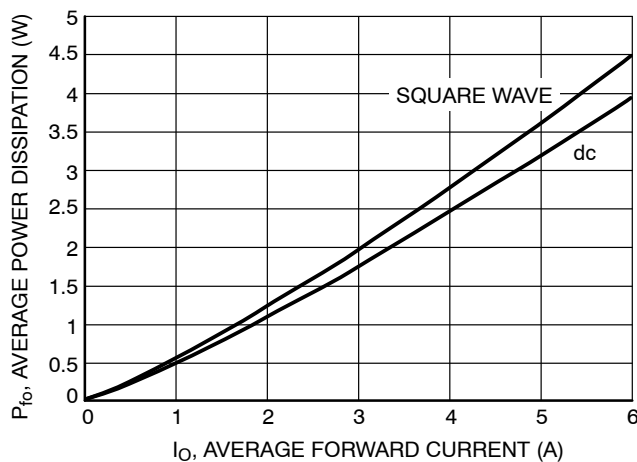


Figure 7. Forward Power Dissipation

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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SCALE 1:1

Polarity Band



SCALE 1:1

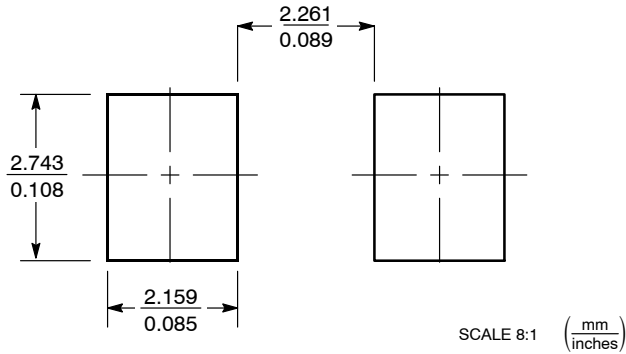
Non-Polarity Band

SMB
CASE 403A-03
ISSUE J

DATE 19 JUL 2012



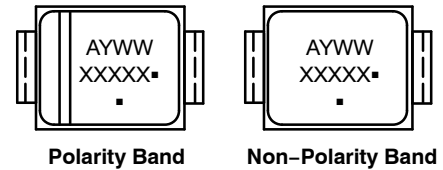
SOLDERING FOOTPRINT*



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.95 | 2.30 | 2.47 | 0.077 | 0.091 | 0.097 |
| A1 | 0.05 | 0.10 | 0.20 | 0.002 | 0.004 | 0.008 |
| b | 1.96 | 2.03 | 2.20 | 0.077 | 0.080 | 0.087 |
| c | 0.15 | 0.23 | 0.31 | 0.006 | 0.009 | 0.012 |
| D | 3.30 | 3.56 | 3.95 | 0.130 | 0.140 | 0.156 |
| E | 4.06 | 4.32 | 4.60 | 0.160 | 0.170 | 0.181 |
| HE | 5.21 | 5.44 | 5.60 | 0.205 | 0.214 | 0.220 |
| L | 0.76 | 1.02 | 1.60 | 0.030 | 0.040 | 0.063 |
| L1 | 0.51 REF | | | 0.020 REF | | |

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
 - A = Assembly Location
 - Y = Year
 - WW = Work Week
 - = Pb-Free Package
- (Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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|-------------------------|--------------------|--|
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| DESCRIPTION: | SMB | PAGE 1 OF 1 |

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